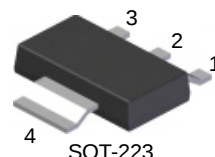


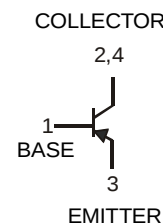
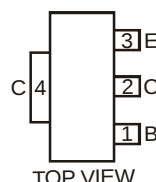
Features

- Epitaxial Planar Die Construction
- Complementary NPN Type Available (DZTA42)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**



Mechanical Data

- Case: SOT-223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish - Matte Tin annealed over Copper Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking & Type Code Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.115 grams (approximate)



Schematic and Pin Configuration

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CB0}	-300	V
Collector-Emitter Voltage	V _{CEO}	-300	V
Emitter-Base Voltage	V _{EBO}	-5	V
Base Current	I _B	-100	mA
Continuous Collector Current	I _C	-500	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation @ T _A = 25°C (Note 3)	P _d	1	W
Thermal Resistance, Junction to Ambient @ T _A = 25°C (Note 3)	R _{θJA}	125	°C/W
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
OFF CHARACTERISTICS (Note 4)						
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-300	—	—	V	I _C = -100μA, I _E = 0
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	-300	—	—	V	I _C = -1mA, I _B = 0
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-5	—	—	V	I _E = -100μA, I _C = 0
Collector-Base Cut-Off Current	I _{CBO}	—	—	-0.25	μA	V _{CB} = -200V, I _E = 0
Emitter-Base Cut-Off Current	I _{EBO}	—	—	-0.1	μA	V _{EB} = -3V, I _C = 0
ON CHARACTERISTICS (Note 4)						
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	—	—	-0.5	V	I _C = -20mA, I _B = -2mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	—	—	-0.9	V	I _C = -20mA, I _B = -2mA
DC Current Gain	h _{FE}	25	—	—	V	I _C = -1mA, V _{CE} = -10V
		40	—	—		I _C = -10mA, V _{CE} = -10V
		25	—	—		I _C = -30mA, V _{CE} = -10V
SMALL SIGNAL CHARACTERISTICS						
Gain-Bandwidth Product	f _T	50	—	—	MHz	I _C = -10mA, V _{CE} = -20V, f = 100MHz
Output Capacitance	C _{obo}	—	—	6	pF	V _{CB} = -20V, f = 1MHz

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on FR-4 PCB, 1" x 0.85" x 0.052"; pad layout as shown on page 4 or on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 4. Measured under pulsed conditions. Pulse Test: Pulse width, tp < 300 μs, Duty Cycle, d < = 2%

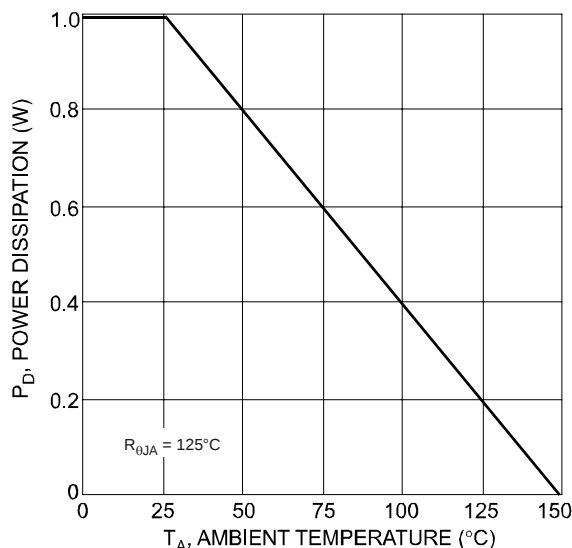


Fig. 1, Power Dissipation vs. Ambient Temperature (Note 3)

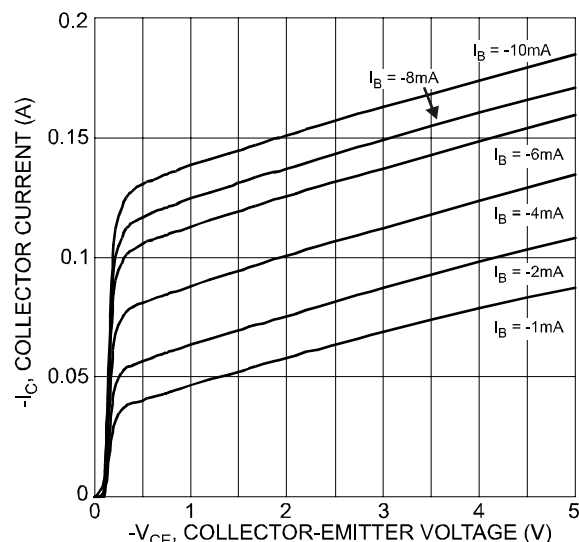


Fig. 2, Typical Collector Current vs. Collector-Emitter Voltage

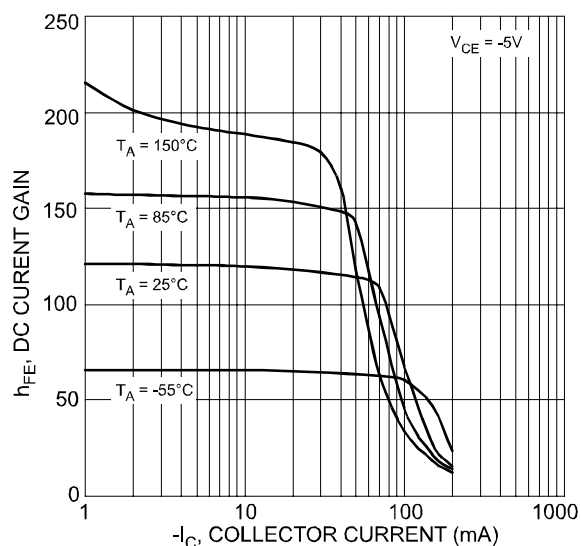


Fig. 3, Typical DC Current Gain vs. Collector Current

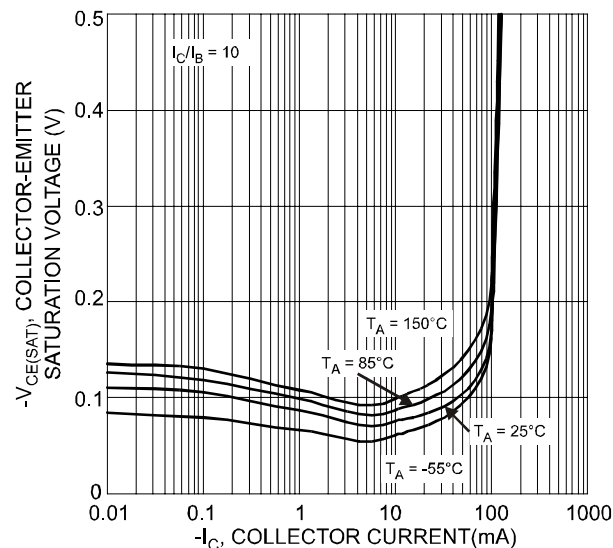


Fig. 4, Typical Collector-Emitter Saturation Voltage vs. Collector Current

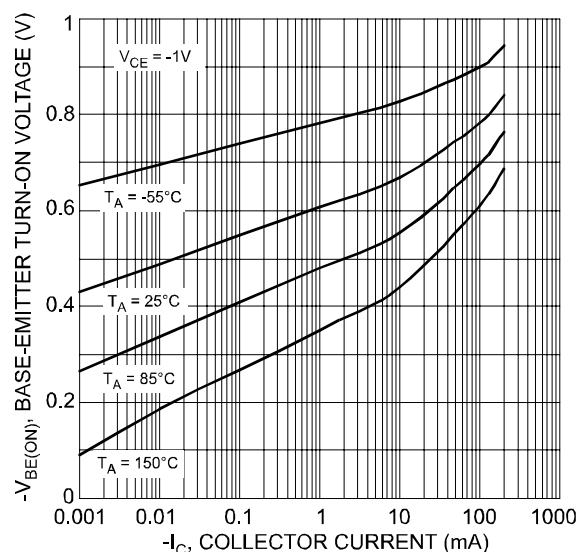


Fig. 5, Typical Base-Emitter Turn-On Voltage vs. Collector Current

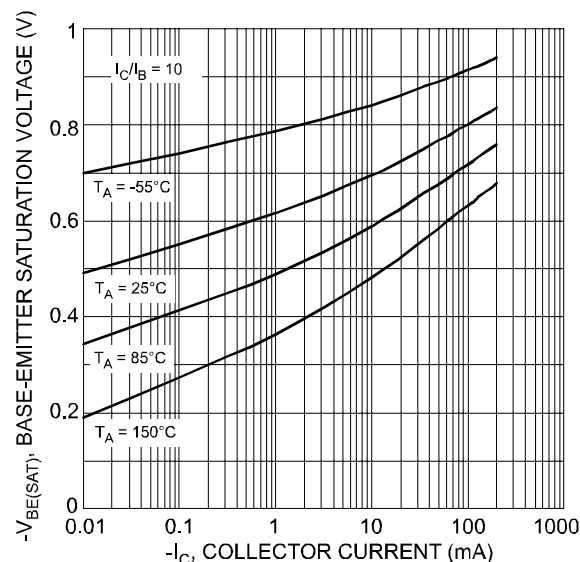


Fig. 6, Typical Base-Emitter Saturation Voltage vs. Collector Current

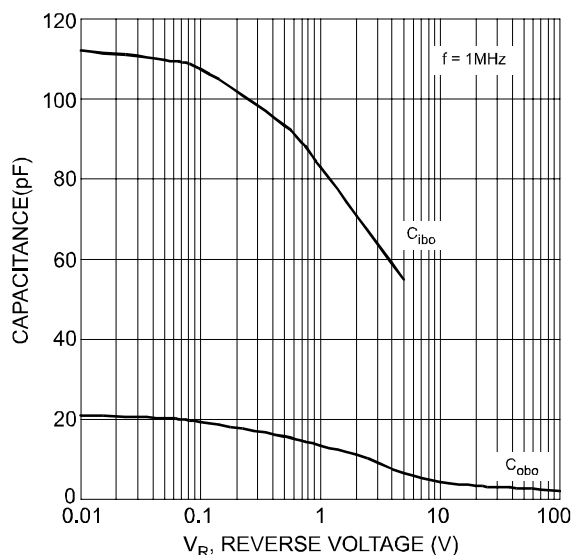


Fig. 7, Typical Capacitance Characteristics

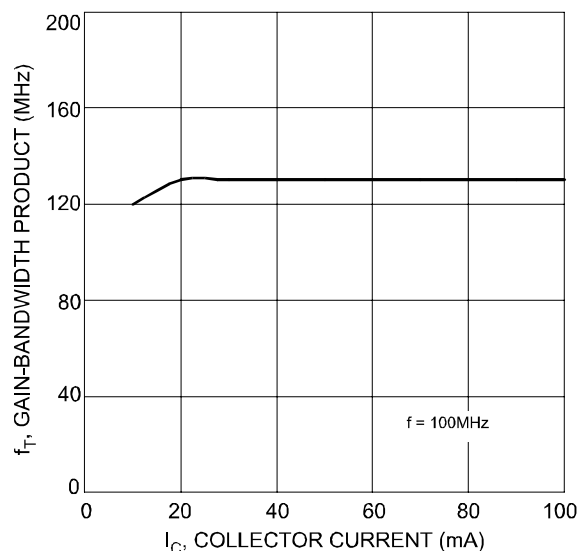


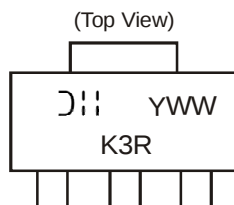
Fig. 8, Typical Gain-Bandwidth Product vs. Collector Current

Ordering Information (Note 5)

Device	Packaging	Shipping
DZTA92-13	SOT-223	2500/Tape & Reel

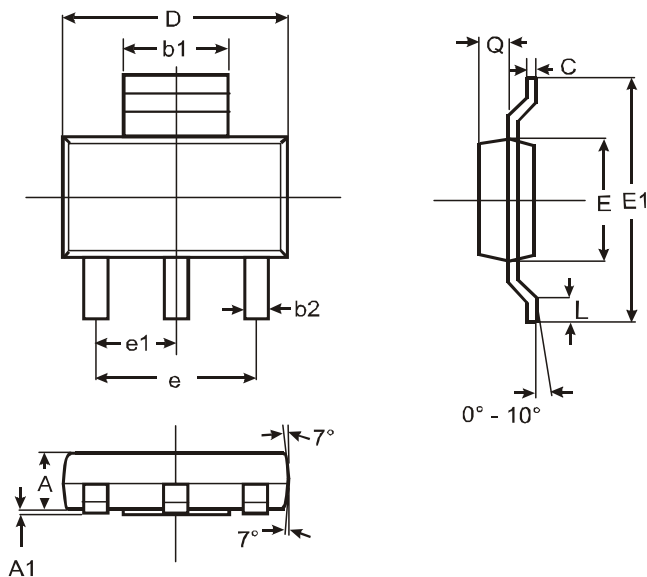
Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information

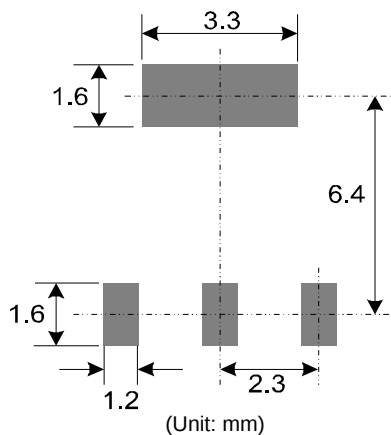


K3R = Product Type Marking Code
YWW = Date Code Marking
Y = Last digit of year ex: 7 = 2007
WW = Week code 01 - 52

Package Outline Dimensions



SOT-223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b1	2.90	3.10	3.00
b2	0.60	0.80	0.70
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	—	—	4.60
e1	—	—	2.30
L	0.55	0.75	0.65
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout: (Based on IPC-SM-782)**IMPORTANT NOTICE**

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